Observation of oxide precipitates in InN nanostructures

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We observed the formation of oxide precipitates (bcc-In₂O₃) in InN nanostructures formed during metal-organic chemical vapor deposition (MOCVD) and/or subsequent postgrowth procedures in H₂ ambient. It was found that InN is extremely unstable in H₂ ambient and the activation energy of N₂ desorption of InN is measured to be ∼0.28 eV, which is one order of magnitude smaller than that of reported value of InN in vacuum. Instability of InN nanostructures under H₂ ambient together with residual oxidant in the reactor facilitates the formation of indium oxide precipitates in the nanostructure matrix during MOCVD or the oxidation of residual indium at the surface, resulting in indium oxide dots. © 2007 American Institute of Physics. [DOI: 10.1063/1.2822396]

Indium nitride (InN) has attracted much attention recently as an important group III-nitride semiconductor. Although thermal instability of InN as well as large lattice and thermal mismatches make the growth of InN films extremely difficult, recent results on InN-based nanostructures are very promising and indicative of potential device applications. However, depending on the growth conditions, there is a possibility of oxide precipitation in such InN nanostructures during growth and/or postgrowth procedures because of high volatility of N₂ from InN surface and high tendency for indium residue on surface to react with background molecular oxygen. It is expected that oxidation would easily occur for indium residue on surface in preference to nitridation by considering the large difference in the heat of formation of InN (34 kcal/mol) compared with In₂O₃ (221 kcal/mol). Generally, InN is grown with N₂ carrier gas or a mixed carrier gas of N₂ and H₂ in metal-organic-chemical vapor deposition (MOCVD) because of expected thermal instability of InN under H₂ ambient. Up to date, there are a few empirical information on this specificity in the growth of InN. However, the role of hydrogen is unclear and speculative in these reports. Therefore, it is desirable to investigate the role of hydrogen in detail in MOCVD growth of InN because hydrogen and hydrogen-containing derivatives are present during InN growth and it will provide a deeper understanding of the underlying chemistry. In this letter, we report the observation of oxide precipitates (bcc-In₂O₃) in InN nanostructures formed during MOCVD and/or postgrowth procedures in H₂ ambient. InN was extremely unstable in H₂ ambient and the appearance of oxide precipitates was very similar to that expected from genuine InN nanostructures, rendering a possibility of false detection.

Two sets of InN nanostructures were grown in commercial horizontal MOCVD reactors. Trimethylgallium, trimethylindium (TMIn), and ammonia (NH₃) were used as Ga, In, and N sources, respectively, whereas both high-purity H₂ and N₂ of 6N (99.99999%) were used as carrier gases. Hydrogen was further purified by a Pd purifier. The first set of InN nanostructures was grown on top of 20-nm-thick cubic GaN (c-GaN)/GaP(100) templates grown at 520 °C in H₂ ambient. The InN dots were grown at growth temperatures in the range of 450–550 °C and the growth pressure was 200 mbar. H₂ carrier gas (7.0 SLM) was introduced throughout the InN growth with NH₃ (3.75 SLM), where SLM stands for standard liters per minute. Immediately after the InN growth, H₂ carrier gas was replaced with N₂ and both N₂ and NH₃ carrier gas (7.0 SLM) and NH₃ (3.75 SLM) were introduced during cooling process to room temperature (RT). The growth rate of InN dots was controlled by TMIn flow rate. The TMIn flow rates were 7.5 and 15 μmol/min, and the corresponding growth times were 45 and 22.5 min, respectively, to keep the total amount of deposition from the gas-phase sources constant in all InN growth at a certain growth temperature. The second set of InN nanostructures is a few monolayer (ML)-thick InN epitaxial layers grown on 2-μm-thick GaN/sapphire(0001) templates. The growth of InN was performed at 730 °C for 90 s and the growth pressure was 300 Torr. All growth conditions were fixed, and TMIn (10 μmol/min) and NH₃ (4.0 SLM) were supplied as precursors and N₂ carrier gas (3.6 SLM) was used. After the InN growth, we varied the cooling environment, one is to keep flowing N₂ carrier gas (3.6 SLM) and NH₃ (4.0 SLM), while the samples was cooled down to RT, and the other is to keep flowing N₂ carrier gas and NH₃ down to 400 °C, followed H₂ carrier gas (7.6 SLM) down to RT.

Figure 1(a) shows a cross-section transmission electron microscope (TEM) image taken for InN dots grown on a c-GaN/GaP(100) template at 450 °C with TMIn flow rate of 15 μmol/min. The indexing of the diffraction pattern (DP) taken from overall structures (not shown here) proved that InN dots grow in zinc-blende structure, where c-InN(100)
planes are parallel to c-GaN(100) planes and hexagonal InN is not present. However, an additional set of diffraction spots was found in this sample. We obtained selective area DPs (SADPs) to determine where they were originated and the additional set of diffraction spots was found only from InN dots, as shown in Figs. 1(b) and 1(c). Based on the corresponding angles and distances between the spots, the coexisting precipitates in InN dots were determined as body centered cubic (bcc)-In$_2$O$_3$. The oxide precipitates were uniformly distributed from the central to the edge area of InN dots from SADPs, and it is reasonable to assume that the oxidation process occurred during MOCVD rather than post-growth process. We supposed that this phenomenon is related to low thermal stability of InN in H$_2$ ambient since hydrogen tends to etch InN and reduces nitrogen sticking coefficient in In(Ga)N, as predicted by thermodynamic calculations.\(^7\)

This hypothesis was tested by growing InN dots with H$_2$ carrier gas on c-GaN/GaP(100) templates at a constant amount of deposition from the gas-phase sources but at different temperatures and growth rates. Growth temperatures were varied from 450 to 550 °C and the calculation of growth rate of InN dots was based on the assumption that the shape of InN dots was a perfect hemisphere. The results are shown in Fig. 2. Higher growth temperature leads to lower growth rate, indicating the strong thermal decomposition of InN during growth, and the activation energy is measured to be $\sim0.28$ eV on the Arrhenius plot. This value is one order of magnitude smaller than the reported activation energy of N$_2$ desorption of InN (or GaN) in vacuum.\(^10,11\) Based on this result, we concluded that the introduction of H$_2$ into the reactor greatly lowered the thermal stability of InN, which enhances the possibility of oxidation of InN.

We also find that surface oxidation of preexisting InN can occur depending on how growth was terminated. A few ML-thick InN was grown on 2-μm-thick GaN/sapphire(0001) template with typical step-flow like feature of atomically flat surface to see the surface morphology of the bare InN layer. After 90 s InN deposition, the sample was cooled down to RT with both N$_2$ and NH$_3$ flows and the resulting sample surface showed the stepped two-dimensional (2D) morphology with the formation of 2D disk-shaped structures on terraces, as shown in Fig. 3(a). Heights of 2D disk-shaped structures were about 3–5 Å as measured by atomic force microscopy (AFM), which are equivalent to 1–2 ML of InN and their diameters were less than 200 nm.\(^12\) However, when N$_2$ carrier gas and NH$_3$ were switched off at 400 °C and the InN specimen was cooled down to RT under H$_2$ ambient, the surface morphology of InN was greatly changed. The quantum dot (QD)-like structures with a density of $2.5 \times 10^9$ cm$^{-2}$ surprisingly appeared on InN surface and most of them existed on 2D disk-shaped structure from AFM measurement, as shown in Fig. 3(b).

From the cross-section TEM images, as shown in Fig. 4, the QD-like structures on InN surface have a different lattice image from underlying GaN template and it turns out to be bcc-In$_2$O$_3$ instead of InN. The interplanar spacing of high resolution lattice fringe image of In$_2$O$_3$ was $\sim2.9$ Å and this corresponds to the reported lattice constant of bcc-In$_2$O$_3$(222).\(^13\) which is in good agreement with a preferential orientation of In$_2$O$_3$ formed by thermal oxidation of InN.\(^14\) We believe that decomposition and desorption of N$_2$ from InN surface were greatly enhanced under H$_2$ ambient during cooling process and the indium residue on the surface would strongly chemisorb background molecular oxygen,\(^5\) resulting in bcc-In$_2$O$_3$ formation mainly on 2D disk-shaped structures.

![FIG. 1.](image1.png) (a) Cross-section TEM image of InN dots grown at 450 °C with TMIn flow rate of 15 μmol/min on 20-nm-thick c-GaN/GaP(100), (b) SADP of the interface between c-GaN buffer (square) and GaP(100) substrate (circle), and (c) SADP of the InN dot (square) with coexisting precipitates bcc-In$_2$O$_3$ (circle).

![FIG. 2.](image2.png) Arrhenius plot of N$_2$ desorption-controlled growth rate of InN dots vs. substrate temperature at a constant amount of deposition from the gas-phase sources.

![FIG. 3.](image3.png) (Color online) 4×4 μm$^2$ AFM images of a few ML-thick InN layers on GaN templates with a cooling environment of (a) N$_2$ carrier gas and NH$_3$ to RT and (b) N$_2$ carrier gas and NH$_3$ down to 400 °C, followed by only H$_2$ carrier gas down to RT. The inset depicts the formation of QD-like structures mostly on 2D disk-shaped structures.

![FIG. 4.](image4.png) Cross-section TEM image of InN dots grown at 450 °C with TMIn flow rate of 15 μmol/min on 20-nm-thick c-GaN/GaP(100), (b) SADP of the interface between c-GaN buffer (square) and GaP(100) substrate (circle), and (c) SADP of the InN dot (square) with coexisting precipitates bcc-In$_2$O$_3$ (circle).
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